ASSOCIATION CONNECTED FRONTES INDUST	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Ty Distribut													
upplier Info	rmation														
Company name*			Company unique ID			ι	Unique ID Authority					Response Date*			
nsemi											2024-04	2024-04-25			
Contact Name		Title - Contact			F	Phone - Contact*				Email -	Email - Contact*				
Product-Env-Ste	wards	Product Enviro Compliance]	NA				Produc	Product-Env-Stewards@onsemi.com				
uthorized Repr	esentative*	Title - Representative			F	Phone - Representative*				Email -	Email - Representative*				
Product-Env-Ste	wards	Product Enviro Compliance			1	NA				Produc	Product-Env-Stewards@onsemi.com				
Reque	ester Item Number	Mfr Item	Item Number Mfr Item Name				Effective Date	Version	Ma	Manufacturing Site		Weight*	UOM	Unit Type	
		SESDL2011PFCT5		Encapsulated DFN			2024-04-25		CN	CNQ).08295	mg	Each	
Ianufacturi n	ng Proccess Informat	ion													
Termir	rminal Plating / Grid Array Material		Terminal Base Alloy J.		J-STD-020 MS	ASL Rating Peak I		ocess Body Temperature Max Time at Peal		eak Temperat	Temperature Number		er of Reflow Cycles		
Sn alloys with no Bi or Zn excluding SnAgCu		CU Alloy		1		260	C	C 30		secon	ds 3	3			
Comments							•	•				•			
vel 1 - maximur	n time at peak temperatu	re during sol	dering is 10-3	0 seconds											
	ation regarding material o														

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Bump	0.0059	mg	Supplier	Tin (Sn)	7440-31-5		0.0044	mg
			Supplier	Copper (Cu)	7440-50-8		0.0015	mg
Die	0.0755	mg	Supplier	Silicon (Si)	7440-21-3		0.0755	mg
Mold Compound-Black	0.00128	mg	Supplier	Hexahydromethylphthalic anhydride	25550-51-0		0.0002	mg
			Supplier	1,6-Bis(2,3-epoxypropoxy)naphthalene	27610-48-6		0.0001	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0001	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.001	mg
			Supplier	Carbon Black (C)	1333-86-4		0	mg
Under Bump Metal	2.7E-4		Supplier	Titanium (Ti)	7440-32-6		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0002	mg